PK095 (v1.4) July 20, 2010

100% Material Declaration Data Sheet FFG1513

Average Weight: 18.5g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					**1.06135**	**5.74**
	Silicon	7440-21-3	100.00		1.06135	
Solder Bump					**0.05432**	**0.29**
	Tin	7440-31-5	63.00		0.03422034	
	Lead	7439-92-1	37.00		0.02009766	
Underfill					**0.0440**	**0.25**
	Epoxy Resin A	9003-36-5	20.00		0.008800	
	Epoxy Resin B	25068-38-6	3.00		0.001320	
	Silica	60676-86-0	70.00		0.030800	
	Hardener	19900-65-3	7.00		0.003080	
Heat Spreader					**3.0000**	**16.22**
	Copper	7440-50-8	99.90		2.99700	
	Nickel	7440-02-0	0.10		0.00300	
Heat Spreader Adhesive					**0.053**	**0.28**
	Organopolysiloxane mixture		100.00		0.053000	
Substrate					**13.32398**	**72.03**
	Copper	7440-50-8	46.91	Metal layer	6.25027996	
	Nickel	7440-02-0	0.52	Metal layer	0.06928471	
	Gold	7440-57-5	0.12	Metal layer	0.01598878	
	BT (core)	13676-54-4/ 25722-66-1	28.00		3.73071496	
	Glass fiber	65997-17-3	10.50		1.39901811	
	Halogen fire retardant	N/A	5.25		0.69950906	
	Solder mask	Trade secret	8.70		1.15918643	
Solder Balls					**0.96318**	**5.21**
	Tin	7440-31-5	95.50		0.91983690	
	Silver	7440-22-4	4.00		0.03852720	
	Copper	7440-50-8	0.50		0.00481590	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/14/06	1.0	Initial Xilinx release.
6/06/06	1.1	100% Material Declaration.
6/19/06	1.2	Updated component descriptions.
9/22/06	1.3	Updated component descriptions and weights.
7/20/10	1.4	Updated Heat Spreader substance description.

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